

# 48 Flux-Cored Wire Activated Rosin Cored Wire for Lead-free and Leaded Alloys

# **Product Description**

Kester 48 Activated Rosin Flux for cored solder wire was developed for lead-free applications to enable soldering of most common metals. 48 has performance characteristics far exceeding standard RA fluxes. 48 builds on the performance of its predecessor Kester 44 with "instant-action" wetting to provide fast and reliable solder joints.

#### **Performance Characteristics:**

- Unparalleled wetting performance
- Excellent solderability and fast wetting to a variety of surface finishes
- Eliminates the need and expense of cleaning
- Low spattering

- Low smoke and odor
- Classified as ROM1 per J-STD-004



#### **RoHS Compliance**

Kester does not determine any applicable Restriction of Hazardous Substances (RoHS) exemptions for our lead containing products at the user level. (Applies only if this core flux is combined with a lead-free alloy)

## **Reliability Properties**

Copper Mirror Corrosion: Low Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Surface Insulation Resistance (SIR), (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2633

	Blank	48
Day 1	1.6*10 <sup>10</sup> Ω	1.1*10 <sup>10</sup> Ω
Day 4	1.2*10 <sup>10</sup> Ω	9.2*10 <sup>9</sup> Ω
Day 7	1.1*10 <sup>10</sup> Ω	8.6*10° Ω

Silver Chromate: Fail

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method

Spread Test (typical): Tested to J-STD-004, IPC-TM-650, Method

Fluorides by Spot Test: Pass Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Chloride and Bromides: 1.05% Tested to J-STD-004, IPC-TM-650, Method

	Area of Spread mm² (in²)	
Flux Core Solder	Sn96.5Ag3.0Cu0.5	Sn63Pb37
285 Mildly Activated Rosin	213 (0.33)	335 (0.52)
275 No-Clean	219 (0.34)	361 (0.56)
44 Activated Rosin	220 (0.34)	342 (0.53)
48 Activated Rosin	245 (0.38)	419 (0.65)

# **Application Notes**





48 flux cored wire is available in a wide variety of alloys, wire diameters and flux percentages and roll sizes. The most common alloys are Sn96.5Ag3.0Cu0.5 and K100LD. Please refer to www.kester.com for wire diameters, flux percentages and roll sizes that are available.

Note: Core Size 50, 58 and 66 = 1.1, 2.2 and 3.3% flux core

### Process Considerations

Solder iron tip temperatures are most commonly between 371-400°C (700-750°F) for lead-free alloys. Heat both the land area and component lead to be soldered with the iron prior to apply the solder wire to the land area or component lead. Do not apply the wire directly to the soldering iron tip. This will shorten the life of the solder tip. If needed, Kester 186 flux may be used as a compatible liquid flux to aid in reworking soldered joints.

# Cleaning

48 possesses excellent fluxing ability, the flux residue is non-corrosive and non-conductive under normal conditions of use. When exposed to an elevated temperature and humidity environment (38°C, 94% RH) for 72 hours, there is no evidence of corrosion caused by the flux residue. IPA will not clean the residues off the surface of the circuit board after the soldering process. A saponifier or cleaning agent specifically designed to clean a rosin based flux is required to clean the residues. Please contact Kester Technical Support for further information.

### Storage and Warranty Period

Storage must be in a dry, non-corrosive environment between 10-40°C (50-104°F). The surface may lose its shine and appear a dull shade of grey. This is a surface phenomenon and is not detrimental to product functionality. Flux-cored solder wire has a limited warranty period determined by the alloy used in the wire. For alloys containing more than 70% lead, the warranty period is 2 years from the date of manufacture. Other alloys have a warranty period of 3 years from the date of manufacture.

#### **⊗**Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet (SDS) and warning label before using this product.